

FIG. 1

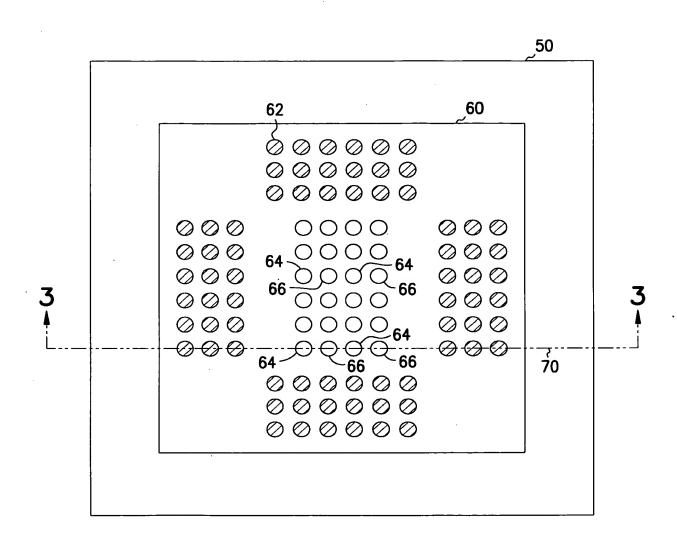
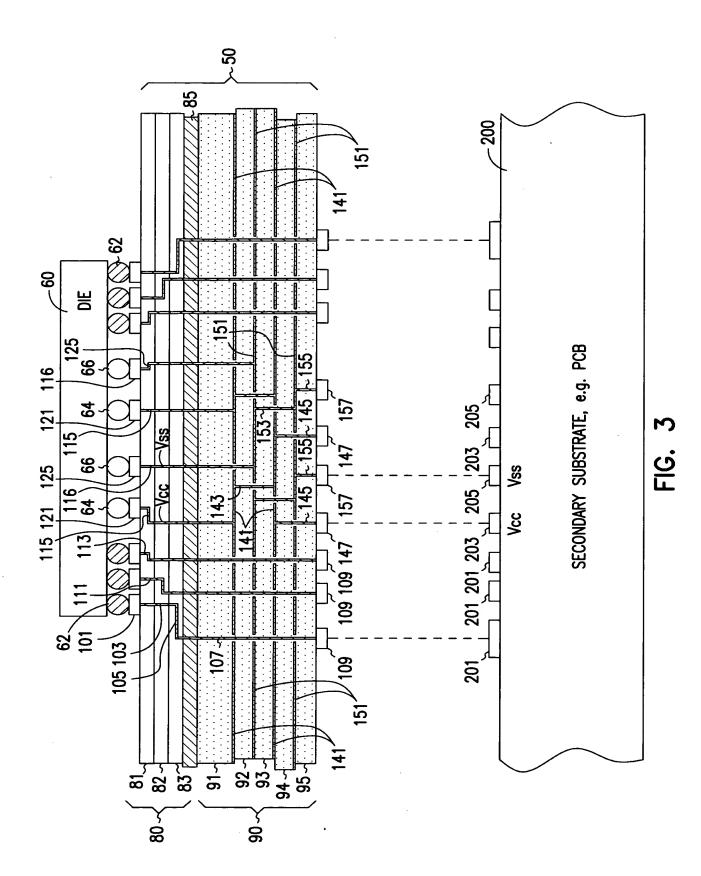
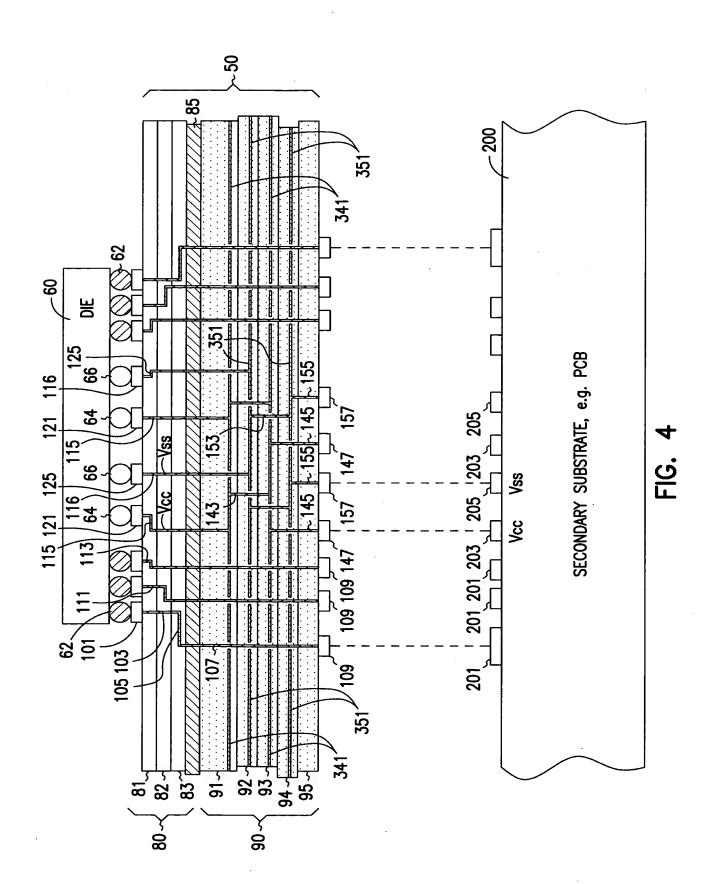


FIG. 2





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FORM FIRST PORTION OF SUBSTRATE USING CERAMIC MATERIALS

THE FIRST PORTION INCLUDES AT LEAST ONE SIGNAL NODE AND AT LEAST ONE CAPACITOR HAVING FIRST AND SECOND TERMINALS

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FORM SECOND PORTION OF THE SUBSTRATE USING ORGANIC MATERIALS

THE SECOND PORTION HAS MULTIPLE CONDUCTORS INCLUDING:
A FIRST CONDUCTOR COUPLED TO THE FIRST TERMINAL,
A SECOND CONDUCTOR COUPLED TO THE SECOND TERMINAL, AND
A THIRD CONDUCTOR COUPLED TO THE SIGNAL NODE

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FORM A FIRST NUMBER OF LANDS ON A SURFACE OF THE SECOND PORTION OF THE SUBSTRATE

THE FIRST NUMBER OF LANDS INCLUDES:
A FIRST LAND COUPLED TO THE FIRST CONDUCTOR,
A SECOND LAND COUPLED TO THE SECOND CONDUCTOR AND
A THIRD LAND COUPLED TO THE THIRD CONDUCTOR

THE FIRST AND SECOND LANDS ARE POSITIONED TO BE COUPLED TO FIRST AND SECOND POWER SUPPLY NODES OF THE DIE. THE THIRD LAND IS POSITIONED TO BE COUPLED TO A SIGNAL NODE OF THE DIE

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FORM A SECOND NUMBER OF LANDS ON A SURFACE OF THE FIRST PORTION OF THE SUBSTRATE

THE SECOND NUMBER OF LANDS INCLUDES:
A FOURTH LAND COUPLED TO THE FIRST CONDUCTOR,
A FIFTH LAND COUPLED TO THE SECOND CONDUCTOR, AND
A SIXTH LAND COUPLED TO THE SIGNAL NODE OF THE FIRST PORTION

THE FOURTH AND FIFTH LANDS ARE POSITIONED TO BE COUPLED TO CORRESPONDING POWER SUPPLY NODES OF A SUBJACENT SUBSTRATE THE SIXTH LAND IS POSITIONED TO BE COUPLED TO A CORRESPONDING SIGNAL NODE OF THE SUBJACENT SUBSTRATE

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WITHIN THE SECOND PORTION OF THE SUBSTRATE, FAN OUT SOME OR ALL OF THE CONDUCTORS FROM A FIRST PITCH OF THE FIRST NUMBER OF LANDS TO A SECOND PITCH OF THE SECOND NUMBER OF LANDS

END ~ 263

FIG. 5